

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1020cn#pbf

(Engineering Calculation)

PDIP

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TOTAL MASS (g) : 0.987648

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004009 | 1000000 | 4059.13964844 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.284310 | 975000 | 287865.78125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.006998 | 24000 | 7085.52197266 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000087 | 300 | 88.0880813599 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000204 | 700 | 206.551376343 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.291599 | 1000000 | 295245.9375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.021727 | 1000000 | 21998.4921875 | | |
| | | External Plating Total: | | | | 0.021727 | 1000000 | 21998.4921875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.002333 | 1000000 | 2362.17822266 | | |
| Internal Plating Total: | | | | 0.002333 | 1000000 | 2362.17822266 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001110 | 750000 | 1123.88232422 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000370 | 250000 | 374.627471924 | | |
| Die Attach Total: | | | | 0.001480 | 1000000 | 1498.5098877 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.159840 | 240000 | 161839.078125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.006660 | 10000 | 6743.29443359 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.479520 | 720000 | 485517.21875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.019980 | 30000 | 20229.8847656 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.666000 | 1000000 | 674329.4375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000500 | 1000000 | 506.253387451 | | |
| | | | | | TOTAL MASS (g) : | 0.987648 | | |